



International Master's Program in Telecommunication Engineering

Course Name:

3D IC Integration Technology and Design for Mobile Devices

移動裝置之三維積體電路的整合技術與設計

Course Objects:

Expose students with the knowledge and analytic capability needed in electronics product design and development.

Course Syllabus:

- Wired and Wireless Communications
- Interconnections
- 3D IC Packaging and Substrates
- RF SiPs
- Intro to PA, Antenna, and FE-Co-design
- Process Characterization: Package-related Failures, DOE, and Failure Analysis
- Product Life and Reliability Assessment